### Vishay Beyschlag



### **Precision Thin Film Chip Resistor Array**





ACAC 0612 (concave terminations) and ACAS 0612 (convex terminations) thin film chip resistor arrays combine the proven reliability of precision thin film chip resistor products with the advantages of chip resistor arrays. Defined tolerance matching and TCR tracking make this product perfectly suited for applications with outstanding requirements towards stable fixed resistor ratios. A small package enables the design of high density circuits in combination with reduction of assembly costs. Four equal resistor values or two pairs are available.

### **FEATURES**

- · Advanced thin film technology
- Two pairs or four equal resistor values
- TCR tracking down to 10 ppm/K (± 5 ppm/K)
- Tolerance matching down to 0.1 % (± 0.05 %)
- Pure Sn termination on Ni barrier layer
- Compliant to RoHS directive 2002/95/EC

### **APPLICATIONS**

- Precision analogue circuits
- · Voltage divider
- · Feedback circuits
- · Signal conditioning

TECHNICAL SPECIFICATIONS					
DESCRIPTION	ACAC 0612, ACAS 0612				
EIA size	0612				
Metric size	RR 1632M				
Configuration, isolated	4 x 0603				
Design:					
All equal	AE				
Two pairs	TP				
Resistance values	47 $\Omega$ to 221 k $\Omega$ <sup>(1)</sup>				
Absolute tolerance	± 0.5 %; ± 0.25 %				
Tolerance matching (2)	0.5 % (equivalent to $\pm$ 0.25 %) 0.25 % (equivalent to $\pm$ 0.125 %) 0.1 % (equivalent to $\pm$ 0.05 %)				
Absolute temperature coefficient	± 50 ppm/K; ± 25 ppm/K				
Temperature coefficient tracking (2)	50 ppm/K (equivalent to $\pm$ 25 ppm/K) 25 ppm/K (equivalent to $\pm$ 12.5 ppm/K) 15 ppm/K (equivalent to $\pm$ 7.5 ppm/K) 10 ppm/K (equivalent to $\pm$ 5 ppm/K)				
Max. resistance ratio $R_{min}/R_{max}$ .	1:5				
Rated dissipation: $P_{70}^{(3)}$					
Element	0.1 W				
Package, 4 x 0603	0.3 W				
Operating voltage	75 V				
Permissibe film temperature	125 °C <sup>(4)</sup>				
Insulation voltage $(U_{ins})$ against ambient and between isolated resistors, continuous	75 V				

#### Notes

- (1) Resistance values to be selected from E24 and E96
- (2) In applications with defined resistance ratios like voltage dividers or feedback circuits, an array with a defined tracking of e.g. 10 ppm/K is required to replace discrete resistors with a temperature coefficient of resistance of ± 5 ppm/K. Furthermore, in order to achieve the same tolerance of ± 0.05 % of individual resistors, an array requires a matching of 0.1 %.
- (3) Please refer to APPLICATION INFORMATION, see below
- (4) For higher max. film temperature and AEC-Q200 qualification please refer to data sheet ACAS 0606 AT, ACAS 0612 AT Precision available on our web site at <a href="https://www.vishay.com/doc?28770">www.vishay.com/doc?28770</a>



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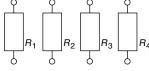
### **APPLICATION INFORMATION**

The power dissipation on the resistor generates a temperature rise against the local ambient, depending on the heat flow support of the printed-circuit board (thermal resistance). The rated dissipation applies only if the permitted film temperature is not exceeded. These resistors do not feature a limited lifetime when operated within the permissible limits.

MAXIMUM RESISTANCE CHANGE AT RATED POWER (1)							
DESCRIPTION	ACAC 0612, ACAS 0612						
Configuration, isolated	4 x	0603					
Operation mode	Precision	Standard					
Rated power per element, P <sub>70</sub>	0.032 W	0.1 W					
Rated power per packaging, P <sub>70</sub>	0.1 W	0.3 W					
Film temperature	85 °C	125 °C					
Operating voltage, <i>U<sub>max.</sub></i> AC/DC	25 V	75 V					
Max. resistance change at $P_{70}$ $\Delta R/R$ max., after:							
1000 h	± 0.1 %	± 0.25 %					
8000 h	± 0.25 %	± 0.5 %					
Max. relative resistance change (relative drift) at $P_{70}$ $\Delta R/R$ max., after:							
1000 h	0.1 % <sup>(2)</sup>	0.25 % <sup>(3)</sup>					
8000 h	0.25 % <sup>(3)</sup>	0.5 % <sup>(4)</sup>					

### Notes

### **SKETCHES**



ACAC 0612, ACAS 0612

DESIGN					
TYPE	ACAC 0612, ACAS 0612				
AE $R_1 = R_2 = R_3 = R_4$					
TP	$R_1 = R_4 < R_2 = R_3$				

<sup>(1)</sup> Figures are given for arrays with equal values, design type AE

 $<sup>^{(2)}</sup>$  Equivalent to  $\pm$  0.05 %

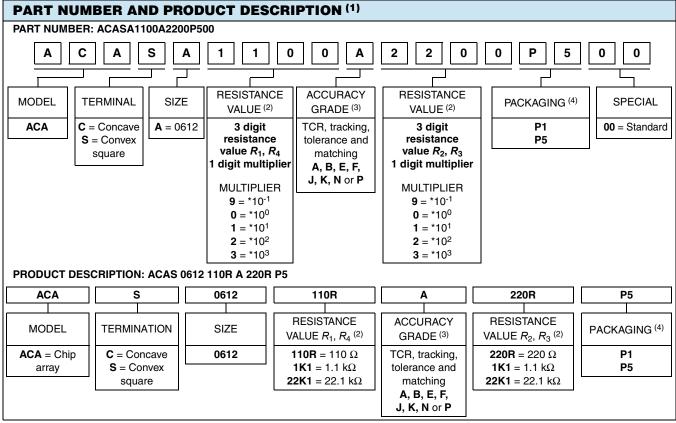
<sup>(3)</sup> Equivalent to ± 0.125 %

<sup>(4)</sup> Equivalent to ± 0.25 %

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### Notes

- (1) Products can be ordered using either the PART NUMBER or the PRODUCT DESCRIPTION
- (2)  $R_1 = R_4 \le R_2 = R_3$
- (3) Please refer to table TEMPERATURE COEFFICIENT AND RESISTANCE RANGE, see below
- (4) Please refer to table PACKAGING, see next page

TEMPERATU	TEMPERATURE COEFFICIENT AND RESISTANCE RANGE							
		DESCRIPTION			RESISTANCE VALUE			
ACCURACY GRADE	ABSOLUTE TCR	TCR TRACKING (5)	ABSOLUTE TOLERANCE	TOLERANCE MATCHING (5)	ACAC 0612, ACAS 0612			
Α	± 25 ppm/K	10 ppm/K	± 0.25 %	0.1 %	47 Ω to 221 kΩ			
В	± 25 ppm/K	10 ppm/K	± 0.5 %	0.25 %	47 Ω to 221 kΩ			
E	± 25 ppm/K	15 ppm/K	± 0.25 %	0.1 %	47 Ω to 221 kΩ			
F	± 25 ppm/K	15 ppm/K	± 0.5 %	0.25 %	47 Ω to 221 kΩ			
J	± 25 ppm/K	25 ppm/K	± 0.25 %	0.1 %	47 Ω to 221 kΩ			
K	± 25 ppm/K	25 ppm/K	± 0.5 %	0.25 %	47 Ω to 221 kΩ			
N	± 50 ppm/K	25 ppm/K	± 0.5 %	0.5 %	47 Ω to 221 kΩ			
Р	± 50 ppm/K	50 ppm/K	± 0.5 %	0.5 %	47 Ω to 221 kΩ			

### Note

<sup>(5)</sup> Please refer to TECHNICAL SPECIFICATIONS, Note (2), see above

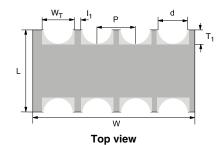


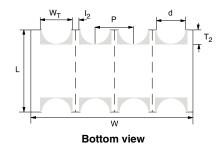
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PACKAGING								
MODEL	TAPE WIDTH	DIAMETER	PIECES	PITCH	PACKAGING CODE			
MODEL	TAPE WIDTH	DIAMETER	FIECES	PITCH	PAPER TAPE			
ACAC 0612	8 mm	180 mm/7"	1000	4 mm	P1			
ACAS 0612	8 mm	180 mm/7"	5000	4 mm	P5			

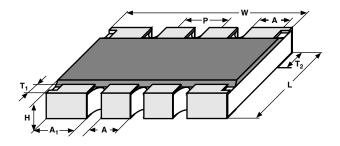
### **DIMENSIONS ACAC 0612**





DIMENSIONS - Chip resistor array, mass and relevant physical dimensions											
TYPE	L (mm)	W (mm)	H (mm)	P (mm)	W <sub>T</sub> (mm)	T <sub>1</sub> (mm)	T <sub>2</sub> (mm)	d (mm)	I <sub>1</sub> (mm)	l <sub>2</sub> (mm)	MASS (mg)
ACAC 0612	1.6 ± 0.15	3.2 ± 0.15	0.55 ± 0.1	0.8 ± 0.1	0.5 ± 0.15	0.3 ± 0.15	0.4 ± 0.15	0.3 ± 0.1	min. 0.15	min. 0.25	9.6

### **DIMENSIONS ACAS 0612**



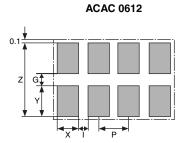
<b>DIMENSIONS</b> - Chip resistor array, mass and relevant physical dimensions									
ТҮРЕ	L (mm)	W (mm)	H (mm)	P (mm)	A <sub>1</sub> (mm)	A (mm)	T <sub>1</sub> (mm)	T <sub>2</sub> (mm)	MASS (mg)
ACAS 0612	1.5 ± 0.15	3.2 ± 0.15	0.45 ± 0.1	0.8 ± 0.1	0.6 ± 0.1	0.4 ± 0.1	0.3 ± 0.15	0.4 ± 0.15	6.6

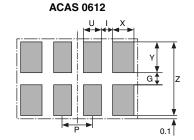
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### PATTERN STYLES FOR CHIP RESISTOR ARRAYS





Dimensions in mm
☐ limits for solder resist

RECOMMENDED SOLDER PAD DIMENSIONS FOR CHIP RESISTOR ARRAYS							
TYPE	G (mm)	Y (mm)	X (mm)	U (mm)	Z (mm)	l (mm)	P (mm)
ACAC 0612	0.7	0.7	0.5	-	2.1	0.3	0.8
ACAS 0612	0.7	0.7	0.64	0.5	2.1	0.3	0.8

### **DESCRIPTION**

The production of the components is strictly controlled and follows an extensive set of instructions established for reproducibility. A homogeneous film of metal alloy is deposited on a high grade (96 % Al<sub>2</sub>O<sub>3</sub>) ceramic substrate using a mask to separate the adjacent resistors and conditioned to achieve the desired temperature coefficient. Specially designed inner contacts are realized on both sides. A special laser is used to achieve the target value by smoothly cutting a meander groove in the resistive layer without damaging the ceramics.

The resistor elements are covered by a protective coating designed for electrical, mechanical and climatic protection. The terminations receive a final pure tin on nickel plating.

The result of the determined production is verified by an extensive testing procedure and optical inspection performed on 100 % of the individual chip resistors. Only accepted products are laid directly into the paper tape in accordance with **IEC 60286-3** <sup>(3)</sup>.

### **ASSEMBLY**

The resistors are suitable for processing on automatic SMD assembly systems. They are suitable for automatic soldering using reflow or vapour phase as shown in **IEC 61760-1** <sup>(3)</sup>. For ACAC resistor arrays automatic soldering using wave can also be used. The encapsulation is resistant to all cleaning solvents commonly used in the electronics industry, including alcohols, esters and aqueous solutions.

The suitability of conformal coatings, if applied, shall be qualified by appropriate means to ensure the long-term stability of the whole system. The resistors are RoHS compliant; the pure tin plating provides compatibility with lead (Pb)-free and lead-containing soldering processes. The permitted storage time is 20 years, whereas the solderability is specified for 2 years after production or requalification. The immunity of the plating against tin whisker growth has been proven under extensive testing.

All products comply with the **GADSL** <sup>(1)</sup> and the **CEFIC-EECA-EICTA** <sup>(2)</sup> list of legal restrictions on hazardous substances. This includes full compliance with the following directives:

- 2000/53/EC End of Vehicle life Directive (ELV) and Annex II (ELV II)
- 2002/95/EC Restriction of the use of Hazardous Substances directive (RoHS)
- 2002/96/EC Waste Electrical and Electronic Equipment Directive (WEEE)

#### **TESTS**

Where applicable, the resistors are tested in accordance with EN 140401-801 which refers to EN 60115-1 and EN 140400.

#### Notes

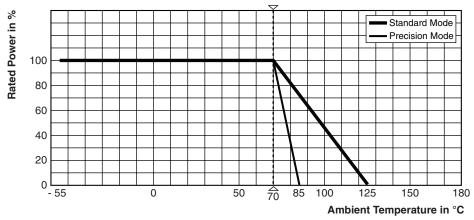
- (1) Global Automotive Declarable Substance List, see www.gadsl.org
- (2) CEFIC (European Chemical Industry Council), EECA (European Electronic Component Manufacturers Association), EICTA (European trade organisation representing the information and communications technology and consumer electronics), see <a href="www.eicta.org">www.eicta.org</a> → policy → environmental policy group → chemicals → jig → Joint Industry Guide (JIG-101 Ed 2.0)
- (3) The quoted IEC standards are also released as EN standards with the same number and identical contents



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### **FUNCTIONAL PERFORMANCE**



For permissible resistance change please refer to table MAXIMUM RESISTANCE CHANGE AT RATED POWER **Derating** 

### **TESTS AND REQUIREMENTS**

Essentially all tests are carried out in accordance with the following specifications:

EN 60115-1, generic specification

EN 140400, sectional specification

EN 140401-801, detail specification

The testing also covers most of the requirements specified by EIA/IS-703 and JIS-C-5202.

The tests are carried out in accordance with **IEC 60068** <sup>(1)</sup> and under standard atmospheric conditions according to **IEC 60068-1** <sup>(1)</sup>, 5.3. Climatic category LCT/UCT/56 (rated temperature range: Lower Category Temperature, Upper

Category Temperature; damp heat, long term, 56 days) is

valid (LCT = -55 °C/UCT = 125 °C).

Unless otherwise specified the following values apply:

Temperature: 15 °C to 35 °C Relative humidity: 45 % to 75 %

Air pressure: 86 kPa to 106 kPa (860 mbar to 1060 mbar)

The requirements stated in the "Test Procedures and Requirements" table are based on the required tests and permitted limits of EN 140401-801 where applicable.

TEST P	TEST PROCEDURES AND REQUIREMENTS						
EN 60115-1 CLAUSE	IEC 60 068-2 <sup>(1)</sup> TEST METHOD	TEST	PROCEDURE	REQUIREMENTS $^{(2)}$ PERMISSIBLE CHANGE ( $\Delta R$ )			
			Stability for product types:				
			ACAC 0612 ACAS 0612	47 $\Omega$ to 221 k $\Omega$ 47 $\Omega$ to 221 k $\Omega$			
4.5	-	Resistance	-	± 0.5 % R; ± 0.25 % R			
4.8.4.2	-	Temperature coefficient	At (20/-55/20) °C and (20/125/20) °C	± 50 ppm/K; ± 25 ppm/K			

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TEST P	TEST PROCEDURES AND REQUIREMENTS						
EN 60115-1 CLAUSE	IEC 60068-2 <sup>(1)</sup> TEST METHOD	TEST	PROCEDURE	REQUIREMENTS $^{(2)}$ PERMISSIBLE CHANGE $(\Delta R)$			
			Stability for product types:				
			ACAC 0612 ACAS 0612	$47~\Omega$ to 221 $k\Omega$ $47~\Omega$ to 221 $k\Omega$			
			$U = \sqrt{P_{70} \times R} \text{ or } U = \text{Umax.};$ 1.5 h on; 0.5 h off;				
		Endurance at 70 °C: Precision operation mode	1000 h: Absolute Relative <sup>(3)</sup>	$\pm$ (0.1 % $R$ + 0.05 $\Omega$ ) 0.1 % $R$ + 0.05 $\Omega$			
4.25.1			8000 h: Absolute Relative <sup>(3)</sup>	$\pm$ (0.25 % $R$ + 0.05 $\Omega$ ) 0.25 % $R$ + 0.05 $\Omega$			
4.25.1	-		$U = \sqrt{P_{70} \times R} \text{ or } U = \text{Umax.};$ 1.5 h on; 0.5 h off;				
		Endurance at 70 °C: Standard operation mode	1000 h: Absolute Relative <sup>(3)</sup>	$\pm$ (0.25 % $R$ + 0.05 $\Omega$ ) 0.25 % $R$ + 0.05 $\Omega$			
		8000 h: Absolute Relative <sup>(3)</sup>	$\pm$ (0.5 % $R$ + 0.05 $\Omega$ ) 0.5 % $R$ + 0.05 $\Omega$				
4.25.3		_	_	_	Endurance at upper	85 °C; 1000 h: Absolute Relative <sup>(3)</sup>	$\pm$ (0.1 % $R$ + 0.05 $\Omega$ ) 0.1 % $R$ + 0.05 $\Omega$
		category temperature	125 °C; 1000 h: Absolute Relative <sup>(3)</sup>	$\pm$ (0.25 % $R$ + 0.05 $\Omega$ ) 0.25 % $R$ + 0.05 $\Omega$			
4.24	78 (Cab)	Damp heat, steady state	(40 ± 2) °C; 56 days; (93 ± 3) % RH	± (0.25 % R + 0.05 Ω)			
4.13	-	Short time overload (4)	$U = 2.5 \times \sqrt{P_{70} \times R}$ or $U = 2 \times U_{\text{max.}}$ ; 5 s	$\pm$ (0.1 % $R$ + 0.01 $\Omega$ ) no visible damage			
4.19	14 (Na)	Rapid change of temperature	30 min at - 55 °C and 30 min at 125 °C; 5 cycles	$\pm$ (0.1 % $R$ + 0.01 $\Omega$ ) no visible damage			
4.18.2	58 (Td)	Resistance to soldering heat	Reflow method 2 (IR/forced gas convention); $(260 \pm 5)$ °C; $(10 \pm 1)$ s	$\pm$ (0.1 % $R$ + 0.01 $\Omega$ ) no visible damage			
	59 /Td\		Solder bath method; SnPb; non-activated flux accelerated ageing 4 h/155 °C (215 ± 3) °C; (3 ± 0.3) s	Good tinning (≥ 95 % covered);			
4.17.2	58 (Td)	Solderability	Solder bath method; SnAgCu; non-activated flux accelerated ageing 4 h/155 °C (235 ± 3) °C; (2 ± 0.2) s	no visible damage			



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TEST P	TEST PROCEDURES AND REQUIREMENTS						
EN 60115-1 CLAUSE	IEC 60 068-2 <sup>(1)</sup> TEST METHOD	TEST	PROCEDURE	REQUIREMENTS $^{(2)}$ PERMISSIBLE CHANGE $(\Delta R)$			
			Stability for product types:				
			ACAC 0612 ACAS 0612	47 $\Omega$ to 221 k $\Omega$ 47 $\Omega$ to 221 k $\Omega$			
4.32	21 (Ue <sub>3</sub> )	Shear (adhesion)	45 N	No visible damage			
4.33	21 (Ue <sub>1</sub> )	Substrate bending	Depth 2 mm, 3 times	$\pm$ (0.1 % $R$ + 0.01 $\Omega$ ) no visible damage; no open circuit in bent position			
4.7	-	Voltage proof	$U_{\rm RMS} = U_{\rm ins}$ (60 ± 5) s; against ambient, between adjacent resistors	No flashover or breakdown			

#### Notes

<sup>(1)</sup> The quoted IEC standards are also released as EN standards with the same number and identical contents

<sup>(2)</sup> Figures are given for arrays with equal values, design type AE

 $<sup>^{(3)}</sup>$  Relative values are equivalent to the half of its value with  $\pm$  symbol, i.e. 0.1 % is equivalent to  $\pm$  0.05 %

<sup>(4)</sup> For a single element



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